



Product/Process Change Notice

PCN # P-2206-0001

Date: 2022/07/18

Dear Customer:

Please be informed that Macronix is going to add 2nd source assembly subcontractor to backup customer original approved assembly subcontractors for 48TSOP package products. The 2nd source assembly subcontractor is ChipMOS.

The detailed information about this change is described in the following pages. This process change has passed Macronix' qualification based on JEDEC standard, and the qualification report is attached below.

If you have any questions, concerns, or requests about this change, please contact your local Macronix Sales Representatives within 30 days, otherwise Macronix will assume customer received the PCN with no comments and the change is acceptable to the customer. Macronix follows JEDEC J-STD-046, it stipulates: ".....Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change".

Thank you.

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(Note: For the customers who receive Macronix PCNs via distributors, Macronix will assist the distributors to convey the PCNs to the customers. It is each distributor's responsibility to communicate and track the responses of each customers and report back to Macronix, the distributor shall assume full responsibilities if failed to do so.)

PCN No.: P-2206-0001

Issue Date : 2022/07/18

Subject: Adding a new assembly vendor—ChipMOS for 48TSOP package products.

Affected Macronix Part No.:

MX30LF1G189C-TI

MX30LF1G18AC-TI

MX30LF1G18AC-TJ

MX30LF1GE8AB-TI

Package type: 48TSOP package products

Change Category : New assembly vendor

Reason of Change:

To increase 48TSOP package assembly capacity and flexibility..

Before Change :

Assembly vendors:

1. SPIL
2. LINGSEN

After Change :

Assembly vendors:

1. SPIL
2. LINGSEN
3. ChipMOS

Product identification:

SPIL assembled IC the marking has vendor code: S

LINGSEN assembled IC the marking has vendor code: L

ChipMOS assembled IC the marking has vendor code: a

Assessment of Change:

1. No impact to Form, Fit, Function, Quality & Reliability.
2. ChipMOS assembled 48TSOP package has passed Macronix' qualification based on JEDEC MSL level 3 standards, and it is also Halogen-Free, and meets the RoHS standards.
* Attached is ChipMOS assembled 48TSOP package qualification report.
3. ChipMOS has been one of Macronix' qualified assembly vendors with good quality for a long time.

Schedule:

Sample available date: 2022/7/31

1st shipping date: 2022/10/31 (Or follow PCN agreement with the customer)



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ChipMOS 48TSOP Package Qualification Report

1. PURPOSE:

To qualify the new assembly subcontractor “ChipMOS” for 48TSOP package.

2. PACKAGE PROFILE:

ASSEMBLY HOUSE	ChipMOS
PACKAGE	48TSOP (12X20 mm)
DIE SIZE	6310 5144 x 3502 μm^2
DIE ATTACH	Nitto EM-760
LEAD FRAME	Copper, Ring Silver
WIRE BOND MATERIAL	Au
MOLD COMPOUND	Showa Denko CEL-9740HF
LEAD FINISH	Matte Sn

3. QUALIFICATION ITEMS, TEST CONDITION AND FLOW:

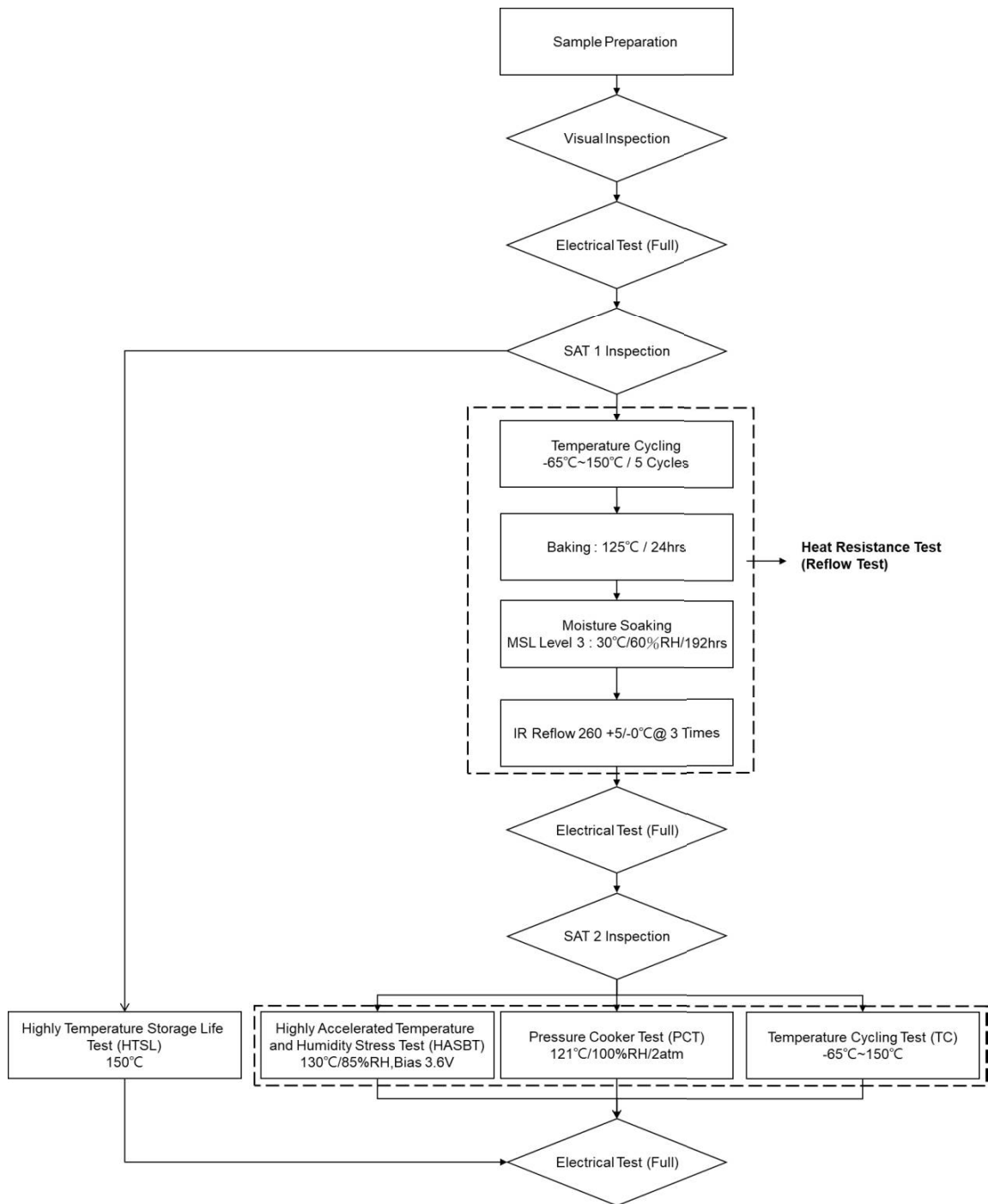
3-1. QUALIFICATION ITEMS:

Test Item	Reference	Test Condition
1. Heat Resistance Test: Reflow Test	JEDEC J-STD-020	MSL: Follow JEDEC MSL Level 3 (30°C/ 60%RH, 192hrs)
2. Pressure Cooker Test	JESD22-A102	121°C/ 100%RH/ 2atm
3. Temperature Cycling Test	JESD22-A104	-65°C ~150°C
4. Highly Accelerated Temperature and Humidity Stress Test	JESD22-A110	130°C/ 85% RH, Bias: 3.6V
5. High Temperature Storage Life Test	JESD22-A103	150°C
6. Solderability Test	JESD22-B102	<ul style="list-style-type: none"> ■ Steam aging 8hrs & Dipping Time \leq 5sec ■ Sn-Ag-Cu solder paste: 245°C ■ Sn-Pb solder paste: 235°C

*Perform SAT examination before and after Preconditioning per JESD22-A112.



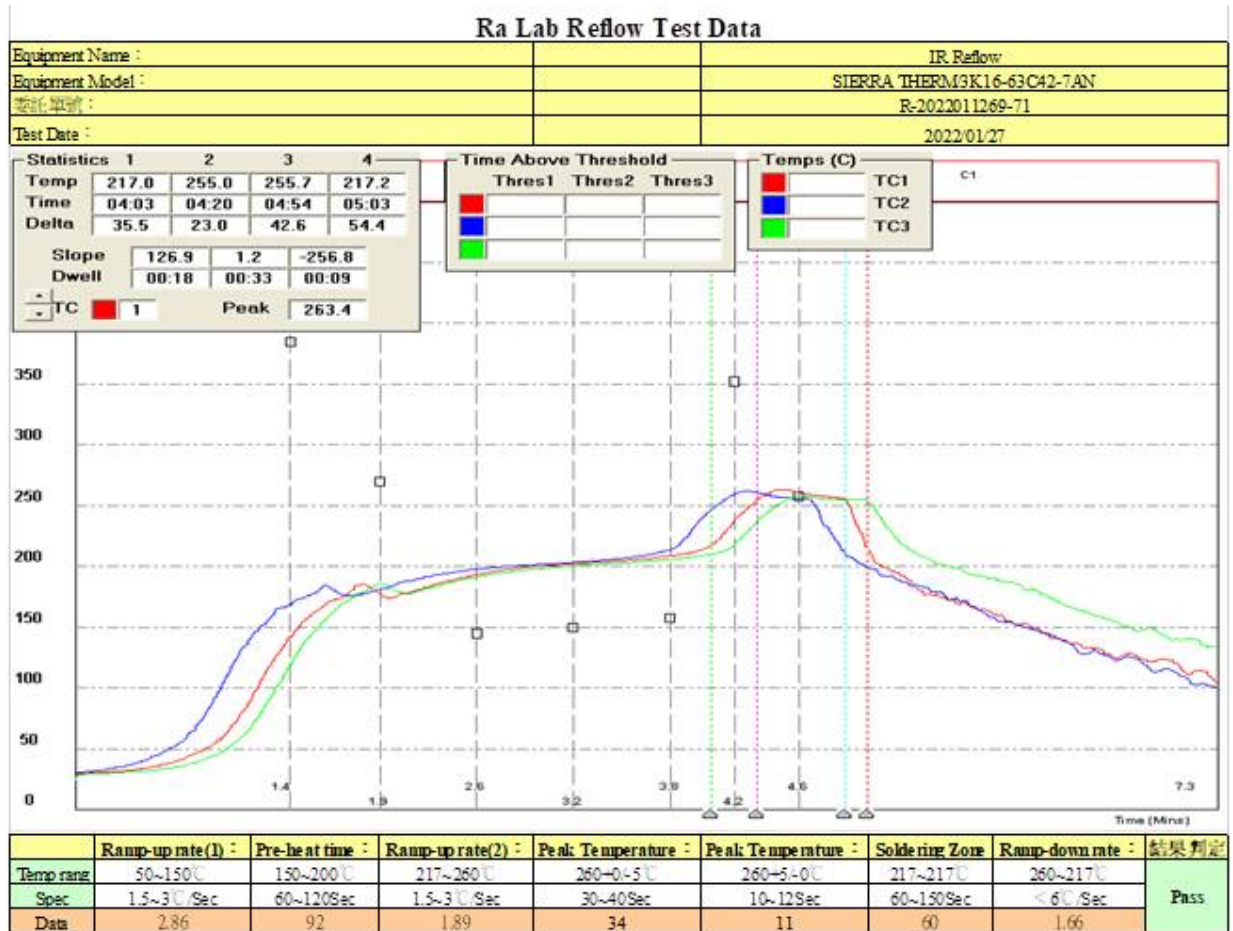
3-2. PRECONDITIONING AND RELIABILITY TEST FLOW:





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3-2-1. REFLOW PROFILE:



Note 1: Subject the samples to 3 cycles of the above defined reflow conditions

Note 2: Time 25°C to peak temperature: 8 minutes max.

Note 3: The time between reflows shall be 5 minutes minimum and 40 minutes maximum.

3-2-2. CRITERIA:

LTPD= 3%, PCT 96 hours and TC 500 cycles and HAST 96 hours

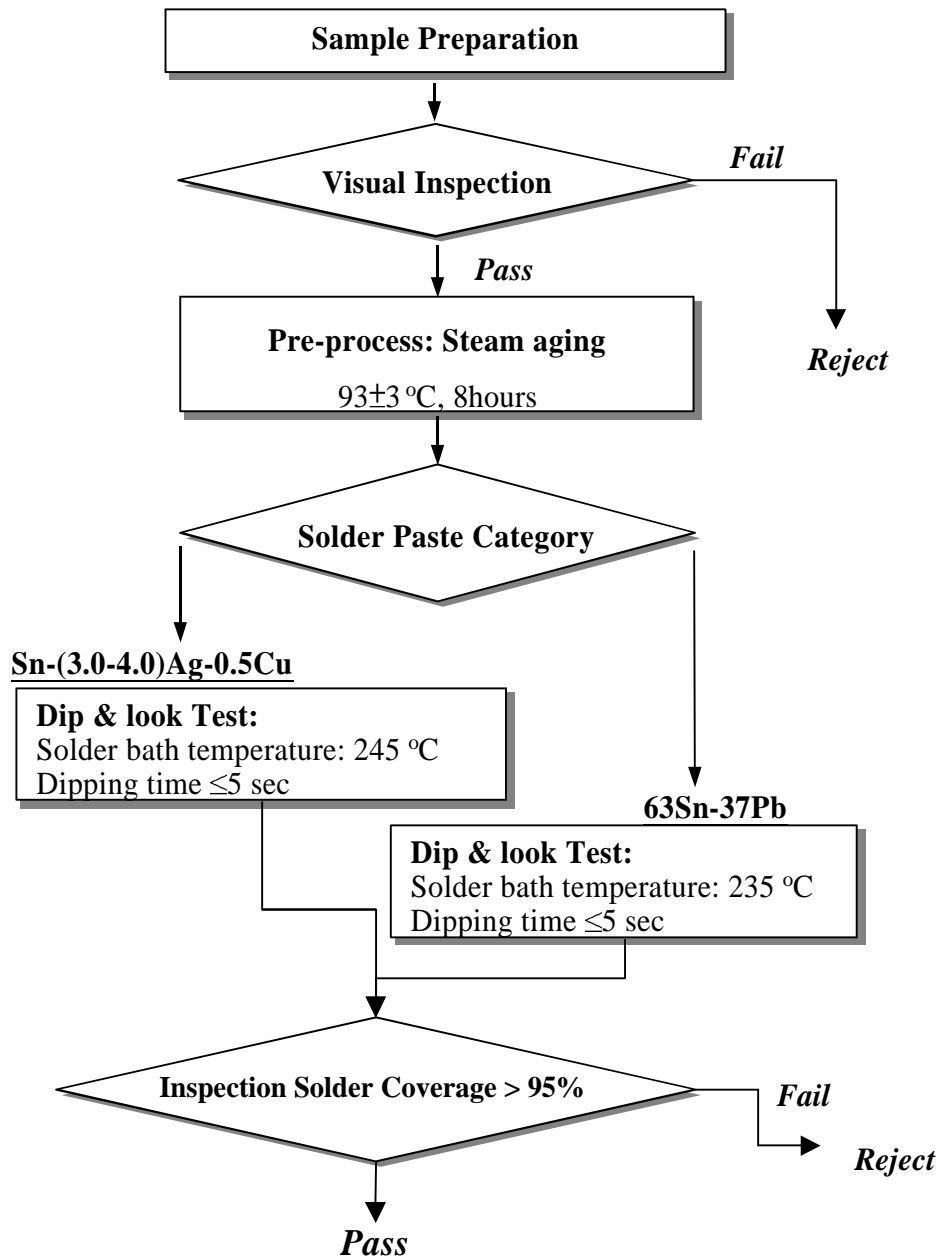
LTPD= 3%, HTSL 1000 hours.

3-2-3. REFERENCE SPECIFICATION:

5650-0901: ASSEMBLY RELIABILITY QUALIFICATION SPEC.



3-3. SOLDERABILITY TEST FLOW




4. RESULTS:
4-1. HEAT RESISTANCE TEST AND RELIABILITY TEST RESULTS:

PRODUCT	6310		
LOT#	8J610500B5	8J610500B6	8J610500B8
DATE CODE	a2150	a2150	a2151
SAT 1	0/22	0/22	0/22
PRECON	0/231	0/231	0/231
SAT 2	0/22	0/22	0/22
PCT 96 HRS	0/77	0/77	0/77
TC 500 CYC	0/77	0/77	0/77
HAST 96 HRS	0/77	0/77	0/77
HTSL 1000 HRS	0/77	0/77	0/77

FAIL / SAMPLE SIZE
4-2. SOLDERABILITY TEST RESULTS:
Matte Sn Plating

Plating Material	Matte Sn		
Solder Paste Material	Sn-(3.0-4.0)Ag-0.5Cu		
INSPECTION	0/5	0/5	0/5

FAIL / SAMPLE SIZE

Plating Material	Matte Sn		
Solder Paste Material	63Sn-37Pb		
INSPECTION	0/5	0/5	0/5

FAIL / SAMPLE SIZE
5. CONCLUSION: PASS

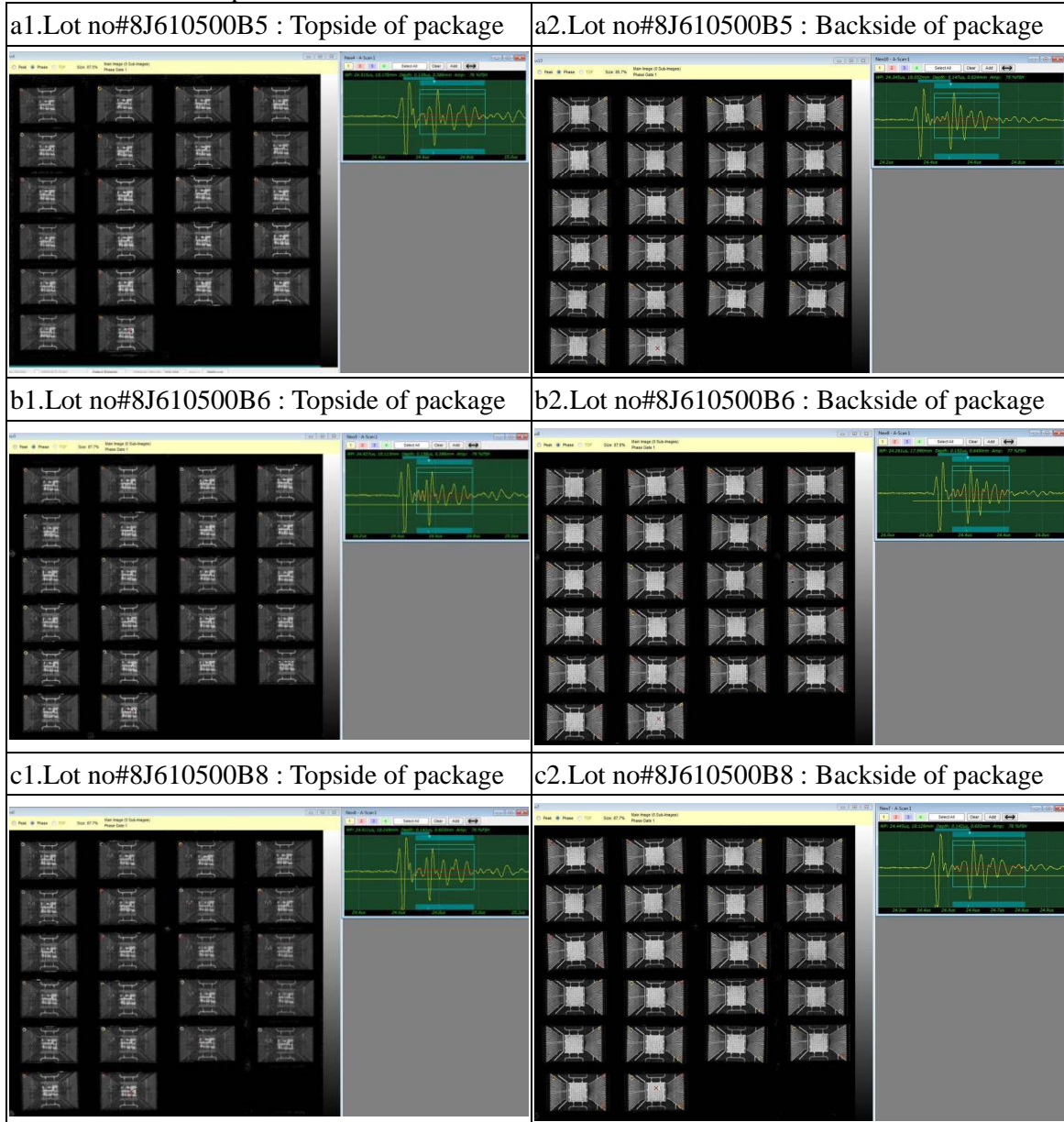


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6. ATTACHED FILE:

6-1. SAT photo

6-1-1. Before pre-condition





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6-1-2. After pre-condition

